FORM PTO-1449 (REV.7-80)

U.S. DEPARTMENT OF COMMERCE 脱 ENT AND TRADEMARK OFFICE

ATTY. DOCKET NO. 34091/US

APPLICANT(S)

APPLICATION NO. 10/783,662

INFORMATION DISCLOSURE STATEMENT
(Use Sea Line Levels of necessary)

Peter C. Salmon

FILING DATE February 20, 2004 GROUP ART UNIT 2823

**U.S. PATENT DOCUMENTS** \*EXAMINER DOCUMENT NUMBER DATE NAME CLASS SUBCLASS FILING DATE INITIAL IF APPROPRIATE 06/19/84 714 28 4,455,654 Bhaskar et al. AA 257 4,748,495 05/31/88 Kucharek 713 ΑB 4,862,322 08/29/89 Bickford et al. 361 718 AC 29 848 4,912,844 04/03/90 Parker ΑD 5,001,548 03/19/91 Iversen 257 714 ΑĒ 361 699 5,159,529 10/27/92 Lovgren 361 5,162,974 11/10/92 Currie 702 ΑG 73 05/25/93 Cayson et al. 438 5,214,250 ΑН 257 714 5,239,200 08/24/93 Messina et al. 439 73 5,267,867 12/07/93 Agahdel et al. 250 5,290,970 03/01/94 Currie 174 Andresen et al. 361 699 5,305,184 04/19/94 216 20 08/02/94 Gregoire ам 5,334,279 Lebby et al. 385 53 5,367,593 11/22/94 ΑN 29 848 02/21/95 Gregoire ΑO 5,390,412 09/19/95 Gregoire 174 261 5,451,722 29 840 5,579,574 12/3/96 Colleran et al. ΑQ 5,627,406 05/06/97 Pace 257 700 714 726 06/30/98 5,774,475 Qureshi 374 104 5,800,060 09/01/98 Speckbrock et al. 324 05/04/99 Khandros et al. 761 5,900,738 ΑU 247 ΑV 5,972,152 10/26/99 Lake et al. 156 174 250 5,998,738 12/07/99 Li et al. AW 174 262 6,005,198 12/21/99 Gregoire AX

**EXAMINER** 

**DATE CONSIDERED** 

\* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).

FORM PTO-1449 (REV.7-80) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTY, DOCKET NO. 34091/US

February 20, 2004

APPLICATION NO. 10/783,662

2823

## INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

APPLICANT(S)
Peter C. Salmon

FILING DATE GROUP ART UNIT

				PATENT DOCUMENTS		<del></del>	1
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
M	AY	6,103,554	08/14/00	Son et al.	438	126	
M	ΛZ	6,121,676	09/19/00	Solberg	257	686	
Un	ВА	6,138,348	10/31/00	Kulesza et al.	29	840	
M	вв	6,174,804	01/16/01	Hsu	438	238	
M	ВС	6,208,511	03/27/01	Bortolini et al.	361	698	
Mu	BD	6,225,688	05/01/01	Kim et al.	257	686	
	BE	6,246,010	06/12/01	Zenner et al.	174	260	
M	BF	6,304,447	10/16/01	Bortolini et al.	361	699	
M	BG	6,310,484	10/30/01	Akram et al.	324	764	
////	вн	6,372,549	04/16/02	Urushima	438	118	
	ВІ	6,441,476	08/27/02	Emoto	257	686	
1//4	ВЈ	6,460,247	10/08/02	Gregoire	29	848	
	вк	6,515,870	02/04/03	Skinner et al.	361	800	
M	BL	6,528,891	03/04/03	Lin et al.	257	778	
	ВМ	6,587,345	07/01/03	Chu et al.	361	719	
M	BN	6,631,344	10/07/03	Kapur et al.	703	22	
MU	во	6,683,377	01/27/04	Shim et al.	257	723	
M	BP	6,722,893	04/20/04	Li et al.	439	66	
lle	BQ	6,763,880	07/20/04	Shih	165	80.4	
	BR	6,845,477	01/18/05	Hidaka	714	729	
Ma	BS	6,881,609	04/19/05	Salmon	438	107	
1	BP	6,927,471	08/09/05	Salmon	257	499	
llx	вU	6,938,678	09/06/05	Bortolini et al.	165	80.4	
M	в٧	6,942,493	09/13/05	Matsunaga et al.	439	66	
EXAMIN	ER	Wan	M	DATE CONSIDERED  Of criteria is in conformance with MAPEP 609. Dra	3		

FORM PTO-1449 (REV.7-80)

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO. 34091/US

APPLICATION NO. 10/783,662

INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

APPLICANT(S)
Peter C. Salmon FILING DATE

GROUP ART UNIT

February 20, 2004 2823

INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE  IF APPROPRIATI
W	вw	6,955,063	10/18/05	Adiga et al.	62	259.2 685	
	вх	6,956,284	10/18/05	Cady et al.	257		
	вч	6,973,717	12/13/05	Hacke et al.	29	840	
na	BZ	6,990,176	01/24/06	Sherman et al.	378	98.8	
	CA	7,009,412	03/07/06	Chong et al.	324	754	
MA	ÇB	7,040,383	05/09/06	Oyamada	165	104.33	
12	СС	7,078,926	07/18/06	Khandros et al.	324	765 18	
11/1	CD	7,163,830	01/16/07	Salmon et al.	438		
	CE	7,254,024	08/07/07	Salmon	361	699	
1/4	CF	US 2002/0030975	03/14/02	Moon	361	749	
M	CG	US 2003/0106004	06/05/03	Richetti et al.	714	733	
M	CH	US 2003/0168725	09/11/03	Warner et al.	257	686	
	СІ	US 2004/0148121	07/29/04	deObaldi et al.	702	117	
Mu	Cì	US 2004/0176924	09/9/04	Salmon	702	125	
	СК	US 2005/0184376	08/25/05	Salmon	257	686	
	CL	US 2005/0255722	11/07/05	Salmon	439	67	
	СМ	US 2006/0077638	04/13/06	Salmon	361	704	
	CN	US 2006/0131728	06/22/06	Salmon	257	698	
	со	US 2006/0209512	09/21/06	Taniguchi et al.	361	699	
W	СР	US 2007/0007983	01/11/07	Salmon	324	754	
	cQ	US 2007/0023889	02/01/07	Salmon	257	690	
M	ÇR	US 2007/0023904	02/01/07	Salmon	385	049	
MN	cs	US 2007/0023923	02/01/07	Salmon	257	296	
	ст	US 2007/0025079	02/01/07	Salmon	361	699	

conformance and not considered. Include copy of this form with next communication to applicant(s).

									Sheet 4	U 4		
FORM PTO-1449 (REV.7-80)			S. DEPARTMENT	· •		APPLICATION NO. 10/783,662						
					APPLICANT(S)							
INFO	)RM	ATION DISCLOSU	Peter C. Salmon									
(Use several sheets if necessary)					FILING DATE February 20, 2004		GROUP ART UNIT 2823					
·	-		FOREI	GN PATEN	T DOCUMENTS							
		DOCUMENT NUMBER DATE		COUNTRY		SS	SUBCLASS	TRANSLATION				
									YES	NO		
lle	DG	JP07169873A	7/4/95	Japan (En	glish abstract)	HOIL	.023	23		X		
	DH						٠					
OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)												
		Chow, Eugene M. et al., "Process Compatible Polysilicon-Based Electrical Through-Wafer										
1111	<b>7</b> 01	Interconnects in Silicon Substrates", Journal of Microelectromechanical Systems, Vol. 11, No.										
		6, December 200										
M	נם	Davis & Arledge, "Thin Film Metallization of Three Dimensional Substrates", Electronic Components Technology Conference, Proceedings 44th, May 1-4, 1994, pp. 359-361										
My	DK	Gutmann, R.J. et al., "Wafer-Level Three-Dimensional Ics: A Better Solution Than SoCs and SiPs?", 6 pages										
m	DL	Holden, Happy, "A Design Technology Innovation – The Power Mesh Architecture for PCBs", The Board Authority, December 2000, pp. 2-6										
// 1		Kreider, Kenneth G. et al., "High Temperature Materials For Thin-Film Thermocouples On										
W	Ďм	Silicon Wafers", Chemical Science and Technology Laboratory, NIST, Gaithersburg, Maryland, USA										
m	Sensu, Yoshihisa et al., "Study on Improved Resolution of Thick Film Resist (Verification									n by		
	DN Simulation)", SPIE, 2001											
EXAMINER DATE CONSIDERED												
4/68 1/4/18												
* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in												
conformance and not considered. Include copy of this form with next communication to applicant(s).												